

PRODUCT SPECIFICATIONS

3535 单波 UVC

◆ Features

- Low Voltage
- High Brightness
- Dimension: 3.5mm* 3.5mm* 1.52mm
- High Luminous Efficiency
- Long Operation Life
- High anti-ESD Ability
- RoHS compliant

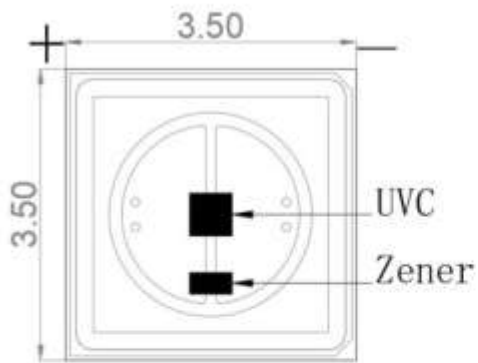


◆ Applications

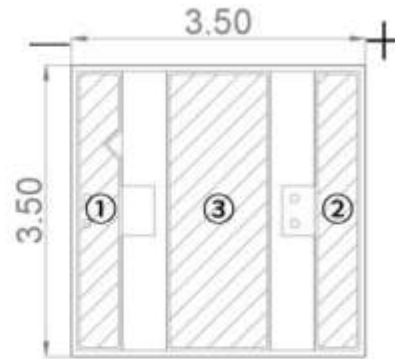
- UV Security Check
- UV Sterilization System
- UV Photo-catalyst
- UV Sensor Light
- UV Jewelry Appraisal
- UV Plant Growth

Mechanical Dimension

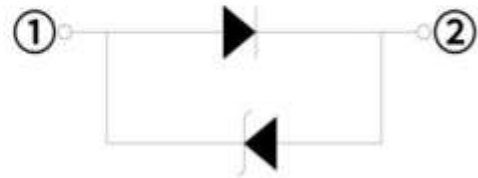
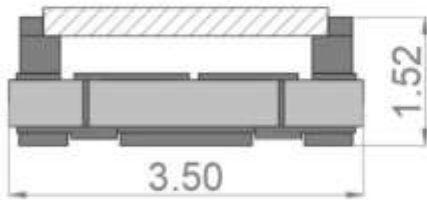
Top View



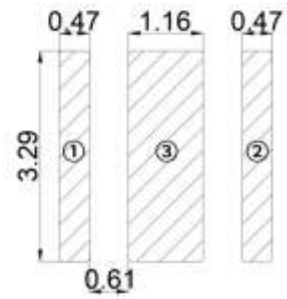
Bottom view



Side View



推荐焊盘



Notes:

1. Dimensions are in millimeters.
2. Tolerances unless mentioned are $\pm 0.2\text{mm}$

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Power Dissipation/DICE	Pd	0.6	W
DC Forward Current/DICE	IF	100	mA
Single Chip Pulsed Forward Current	IFP	150	mA
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-30 ~ +60	°C
Storage Temperature	Tstg	-40 ~ +100	°C

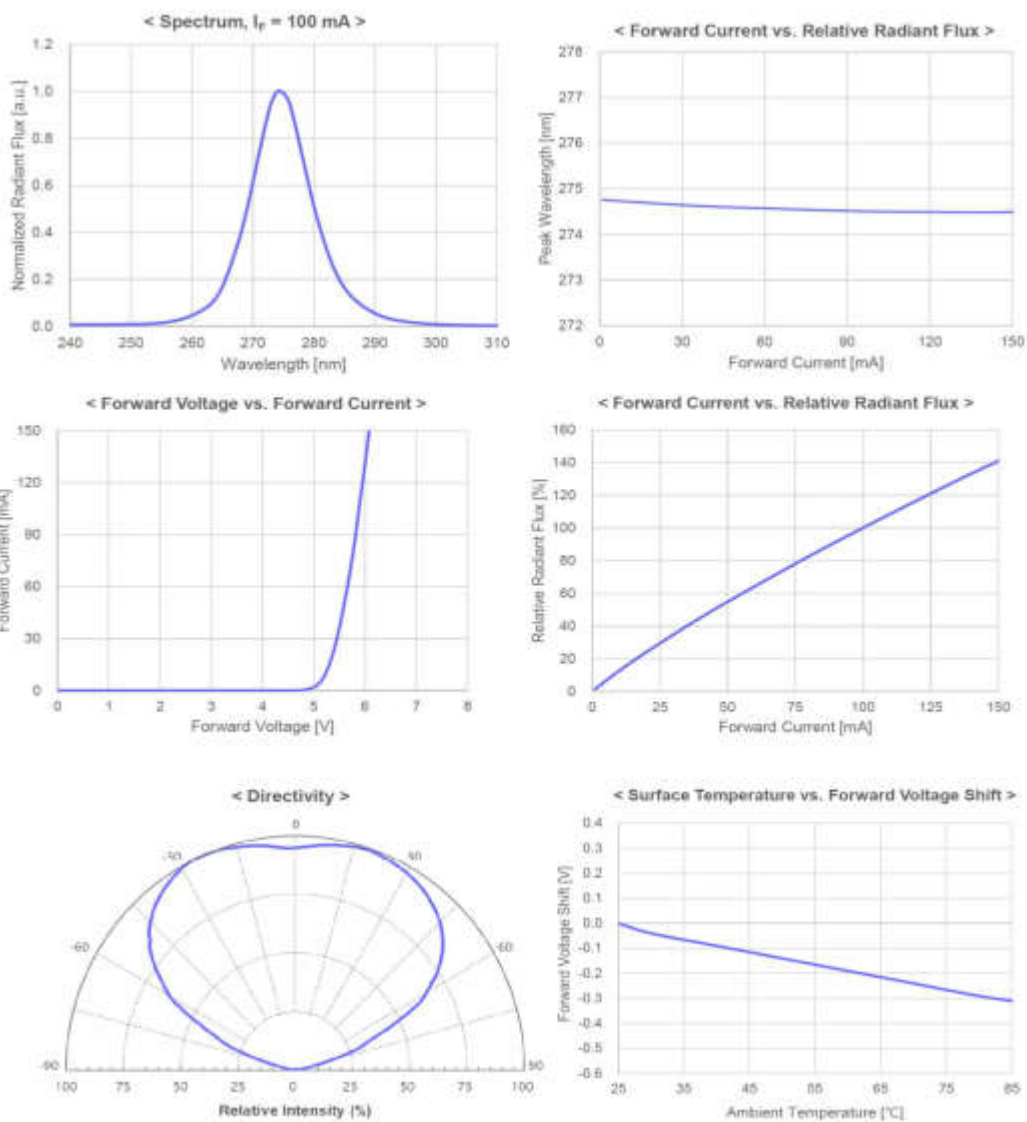
Electro-Optical Characteristic

Parameter	Symbol	Value			Unit	Test condition
		Min.	Typ.	Max.		
Forward Voltage	Vf	5.0	6.0	7.0	V	If=100mA
Reverse Current	Ir	-	-	10	μA	Vr=5V
Viewing angle	2θ1/2	-	120	-	Deg	If=100mA
Peak wavelength	λP	270	275	280	nm	If=100mA
Luminous Flux	Φe	10	-	25	mW	If=100mA

Notes:

1. Radiant flux measurement tolerance: ±10%.
2. The data of luminous flux measured at thermal pad=25°C
3. Typical radiant flux or light output performance is operated within the condition guided by this datasheet.

Typical Characteristics Curves



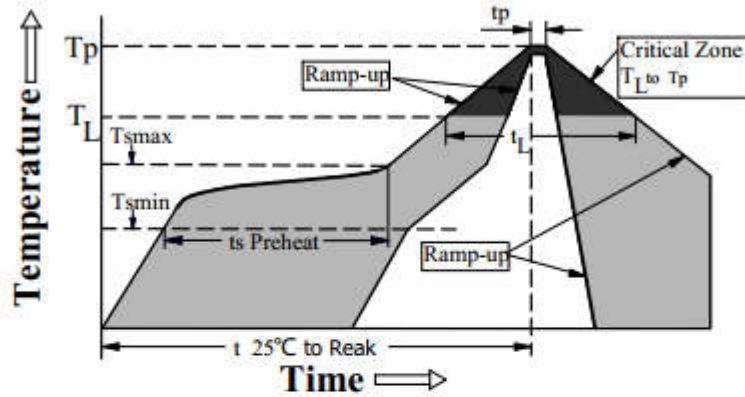
● Soldering :

1. Manual Soldering

The temperature of the iron tip should not be higher than 350°C and Soldering time to be within 3 seconds per solder-pad.

2. Reflow Soldering Characteristics

Temperature Profile



Profile Feature	Sn-Pb Eutectic Assembly
Average Ramp-Up Rate (T_{smax} to T_p)	3°C / second max.
Preheat Temperature Min. (T_{smin})	100°C
Preheat Temperature Max. (T_{smax})	150°C
Preheat Time (t_{smin} to t_{smax})	60-120 seconds
Time Maintained Above Temperature (T_L)	183°C
Time Maintained Above Time (t_L)	60-150 seconds
Peak / Classification Temperature (T_p)	220°C
Time Within 5°C of Actual Peak Temperature (t_p)	10-30 seconds
Ramp – Down Rate	6°C / second max.
Time 25°C to Peak Temperature	6 minutes max.

Notes: 1. All temperature refer to the application Printed Circuit Board (PLCC), measured on the surface adjacent to the package body.